



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-08-07
Contact Name *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Authorized Representative *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement	
Supplier Acceptance *	Legal Declaration *
true	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD25NF10T4	XNDP*QD0FB3F	A	998G	2018-08-07
Amount	UoM	Unit type	ST ECOPACK Grade	
330.00	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	1.14	Die - Leadframe	3467
Lead	5.53	Soft solder	16761

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	5.53	soft solder	16761
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	5.53	soft solder	924916

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	XNDP*QD0FB3F					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	6.556	mg	supplier	die	Silicon (Si)	7440-21-3		6.316	mg	963398	19142
				supplier	metallization	Aluminium (Al)	7429-90-5		0.123	mg	18759	373
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	150	3
				supplier	Passivation	Silicon Oxide	7631-86-9		0.058	mg	8846	176
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	458	9
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.037	mg	5643	112
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.003	mg	458	9
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.015	mg	2288	40
Leadframe	M-004 Copper and its alloys	166.051	mg	supplier	alloy	Copper (Cu)	7440-50-8		164.729	mg	992039	499179
				supplier	alloy	Iron (Fe)	7439-89-6		0.165	mg	994	500
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.050	mg	300	152
				supplier	metallization	Nickel (Ni)	7440-02-0		1.107	mg	6667	3355
Soft solder	Solder	5.980	mg	SVHC	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	5.531	mg	924916	16761
				supplier	solder	Tin (Sn)	7440-31-5		0.299	mg	50000	906
				supplier	solder	Silver (Ag)	7440-22-4		0.150	mg	25084	455
Bonding wires	M-011 Other inorganic materials	1.847	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.847	mg	1000000	5597
Encapsulation	M-011 Other inorganic materials	148.521	mg	supplier	mold compound	Silica, vitreous	60676-86-0		129.955	mg	874994	393803
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-bis	EC 413-900-7		5.941	mg	40001	18003
				supplier	mold compound	Epoxy Resin	25068-38-6		4.456	mg	30002	13503
				supplier	mold compound	phenol resin	29690-82-2		7.426	mg	50000	22503
				supplier	mold compound	Carbon black	1333-86-4		0.743	mg	5003	2252
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3167